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ER SHEET



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JCE79 U.S. PTO
10/439724
06/16/03

To: Honorable Commissioner of Patents and Trademarks

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)

a) Jason Liang

5.16.03

2. Name and address of receiving party(ies):

a) Name: International Business Machines Corporation
Address: New Orchard Road
Armonk, New York 10504

3. Nature of conveyance



Assignment



Merger



Security Agreement



Change of Name



Other _____



License Agreement

Execution Date: May 13, 2003

4. Application Number(s) or Patent Number(s): Unassigned

The title of the (new) application is:

10439724

**METHOD AND APPARATUS FOR MEASURING FLATNESS AND/OR RELATIVE
ANGLE BETWEEN TOP AND BOTTOM SURFACES OF A CHIP**

5. Please send all correspondence concerning this (these) documents to:

Silicon Valley IP Group, LLC.
P.O. Box 721120
San Jose, California 95172-1120

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00



Enclosed

Authorized to be charged to Deposit Account No. 09-0466
(Order No. SJ09-2003-0015US1/IBM1P035)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date:

5/16/03

Dominic M. Kotab
Registration No. 42,762

05/23/2003 6TON11 00000146 090466 10439724

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Attorney Docket No. SJ09-2003-0015US1/IBM1P035

(Revised 01/96)

PATENT
REEL: 014088 FRAME: 0672

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:

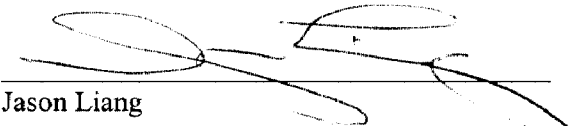
METHOD AND APPARATUS FOR MEASURING FLATNESS AND/OR RELATIVE ANGLE BETWEEN TOP AND BOTTOM SURFACES OF A CHIP

(Atty. Docket No.: IBM1P035/SJO9-2003-0015US1) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to **INTERNATIONAL BUSINESS MACHINES CORPORATION**, a New York corporation having a place of business at Armonk, New York, 10504, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

1) Signature: 
Typed Name: Jason Liang

Date: 5/13/03

Attny Docket No. IBM1P035/SJO9-2003-0015US1

RECORDED: 05/16/2003

PATENT
REEL: 014088 FRAME: 0673